



M14C04 Die Description

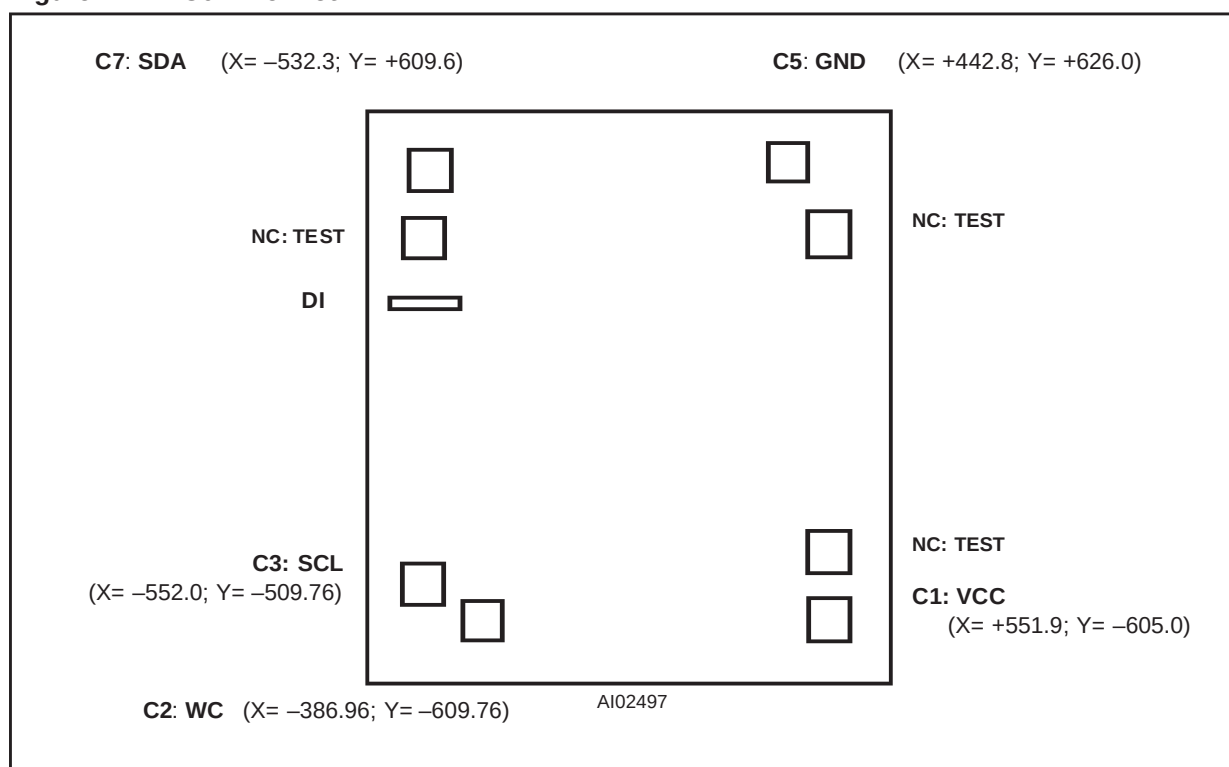
PRODUCT	M14C04
■ WAFER SIZE	152 mm (6 inches)
■ DIE IDENTIFICATION	M14C04KA_R
■ DIE SIZE (X x Y)	1465 x 1585 μm
■ SCRIBE LINE	101.6 x 101.6 μm
■ PAD OPENING	100 x 100 μm

DIE LAYOUT

- DI Die Identification (at the position shown in Figure 1)
- C1, C2, C3, C5, C7 Pad contacts to the ISO pins (at the positions shown in Figure 1)
- C4, C6, C8 These ISO pins do not appear on the M14C04 die
- NC This pad, shown in Figure 1, is Not Connected

Pad locations are measured relative to the die centre (where X and Y are respectively the horizontal and vertical axis, measured in μm).

Figure 1. M14C04 Die Plot



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